

Specification

Drawing No.	TNY1T-H1-16553-00 [1/10]
Issued Date.	Jul-27-2016

TO: AVX Corporation

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Crystal Oscillator
Product Model	_____
Frequency	24 MHz
Customer Part Number	_____
Customer Specification Number	_____
KYOCERA Part Number	MC2016K24.0000C16ESH
Remarks	RoHS Compliant / MSL 1 / AEC-Q200 & Q100 Certified

Customer Acceptance

Accept Signature	Accept Date	
	Department	
	Person in charge	

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Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Oscillator Division	M. Fukawa	H.Yotsuzuka	M. Ishibashi	K.Shimura

Revision History

Rev. No.	Description of revise	Date	Approved by	Checked by	Issued by
00	First Edition	Jul-27-2016	H.Yotsuzuka	M. Ishibashi	K.Shimura

1. Scope

This specification shall be defined of the Clock Oscillator for the integrated circuits (ICs).

2. Customer Part Number**3. KYOCERA Part Number****MC2016K24.0000C16ESH****4. Electrical Characteristics****4-1. Absolute Maximum Rating**

Item	Symbol	Rated Value	Units
Power Supply Voltage	V_{CC}	-0.3 to +4.0	V
Input Voltage	V_{IN}	-0.3 to $V_{CC} + 0.3$	V
Storage Temperature	T_{STG}	-55 to +125	°C

Note:

If the part is used beyond absolute maximum ratings, it may cause internal destruction. The part should be used under the recommended operating conditions the reliability of this part may be damaged if those conditions are exceeded.

4-2. Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Units	Remarks
Power Supply Voltage	V_{CC}	1.6	3.3	3.63	V	
Input Voltage	V_{IN}	0	---	V_{CC}	V	
Operating Temperature	T_{OPR}	-40	+25	+105	°C	

4-3. Electrical Characteristics

Item	Symbol	Min	Typ	Max	Units	Remarks
Output Frequency	F_O	---	24	---	MHz	
Frequency Tolerance*	F_{tol}	-50	---	+50	ppm	
Current Consumption (Loaded/ $1.6 \leq V_{CC} \leq 2.25V$)	I_{CC}	---	---	2.5	mA	
Current Consumption (Loaded/ $2.25 < V_{CC} \leq 2.8V$)		---	---	3.0		
Current Consumption (Loaded/ $2.8 < V_{CC} \leq 3.63V$)		---	---	3.5		
Standby Current	I_{ST}	---	---	5	μA	
Symmetry (Duty Ratio)	SYM	45	50	55	%	@ 50% V_{CC}
Rise Time/ Fall Time (10% V_{CC} to 90% V_{CC})	T_r / T_f	---	---	6.0	ns	$1.6 \leq V_{CC} \leq 2.25V$
		---	---	5.0		$2.25 < V_{CC} \leq 2.8V$
		---	---	4.5		$2.8 < V_{CC} \leq 3.63V$
Output Voltage-"L"	V_{OL}	---	---	10% V_{CC}	V	$I_{OL} = 4mA$
Output Voltage-"H"	V_{OH}	90% V_{CC}	---	---	V	$I_{OH} = -4mA$
Output Load	CL	---	---	15	pF	CMOS
Input Voltage-"L"	V_{IL}	---	---	30% V_{CC}	V	
Input Voltage-"H"	V_{IH}	70% V_{CC}	---	---		
Output Disable Time	t_{dis}	---	---	200	ns	
Output Enable Time	t_{ena}	---	---	5	ms	
Start-up Time	t_{sta}	---	---	5	ms	@ Minimum operating voltage to be 0sec
1 Sigma Jitter**	J_{Sigma}	---	---	5	ps	
Peak to Peak Jitter**	J_{PK-PK}	---	---	50		
Phase Jitter	---	---	---	1	ps	BW:12kHz to 20MHz

Note: All electrical characteristics have defined on the maximum loaded and recommended operating conditions.

* Include initial tolerance, operating temperature range, rated power supply voltage change, load change, aging (1year @+25°C), shock and vibration

**Based on Time Interval Analyzer "Wavecrest SIA-3000".

Table 1

4-4. Measurement Condition

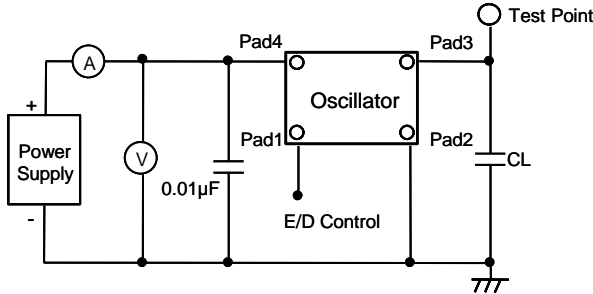
The reference temperature shall be $+25 \pm 2^\circ\text{C}$. The measurement shall be performed at the temperature range of $+5^\circ\text{C}$ to $+35^\circ\text{C}$ unless otherwise the result is doubtful.

4-5. Measurement Circuit

The electrical characteristics shall be measured by test circuit "Fig. 1". Also jitter shall be measured by test circuit "Fig. 3".

4-6. Clock Timing Chart

The clock timing chart is "Fig. 2".



Note: CL includes probe and test fixture capacitance

Fig.1 Test Circuits

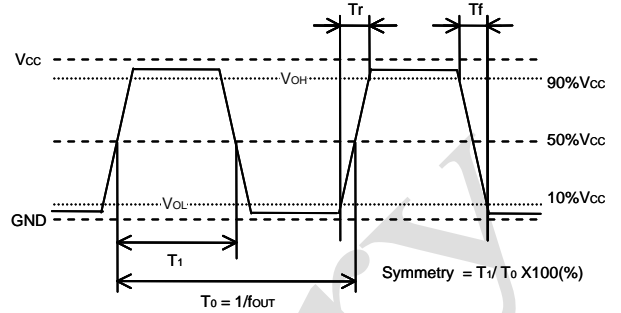
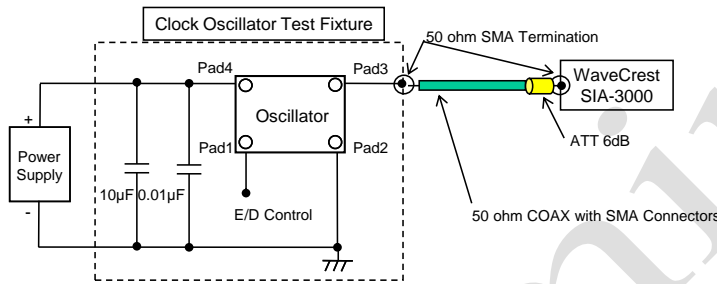


Fig.2 Clock Timing Chart (C-MOS Output)

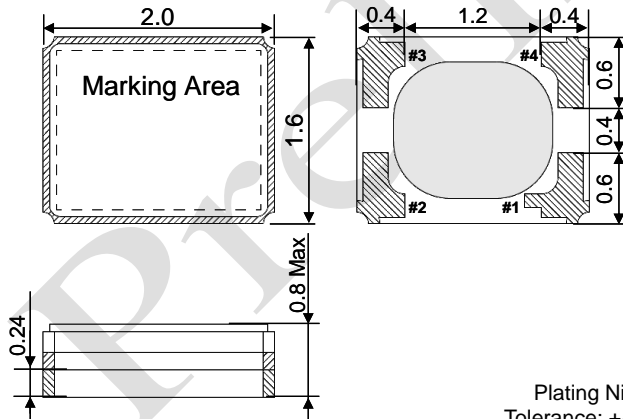


<Measurement Conditions>

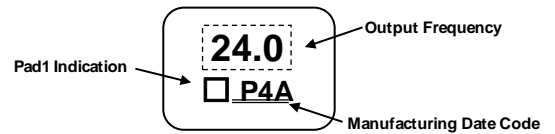
- Time Interval Analyzer
 - WaveCrest SIA-3000
- DTS timer calibration
 - Over 30 minutes warm-up
 - Extend 30 minutes calibration
- Jitter histogram conditions (Tail-fit)
 - More than 50,000cyc Hits
 - Bit Error Ratio (BER) -12 (14sigma)

Fig.3 Jitter Test Circuits

5. Dimensions and Marking



Plating Ni+Au
Tolerance: ± 0.2
Unit: (mm)



Output Frequency

The output frequency is three-digit without a decimal point. The frequency greater than the number of digits have rounded down.

(E.g. 14.31818MHz \rightarrow "14.3")

Manufacturing Date Code

Year	Code	Year	Code	Month	Code	Day	Code	Day	Code	Day	Code
2001	A	2011	L	1	1	1	1	11	B	21	M
2002	B	2012	M	2	2	2	2	12	C	22	N
2003	C	2013	N	3	3	3	3	13	D	23	P
2004	D	2014	P	4	4	4	4	14	E	24	Q
2005	E	2015	Q	5	5	5	5	15	F	25	R
2006	F	2016	R	6	6	6	6	16	G	26	S
2007	G	2017	S	7	7	7	7	17	H	27	T
2008	H	2018	T	8	8	8	8	18	J	28	V
2009	J	2019	V	9	9	9	9	19	K	29	W
2010	K	2020	W	10	A	10	A	20	L	30	X
				11	B					31	Y
				12	C						

It repeats from A in 2021 and afterwards.

e.g. : "P4A" means "Apr-10-2014"

Table 2

Pad arrangement	
1	Enable/Disable
2	Case GND
3	Output
4	Vcc

Enable/Disable Function	
Pad1	Pad3 (Output)
OPEN	Active
"H" Level	Active
"L" Level	High Z (No-Oscillation)

6. Parts Numbering Guide

MC2016K24.0000 C 1 6 E SH
 A B C D E F G

- A. Series (SMD Oscillator)
 B. Output Frequency
 C. Output
 C: C-MOS
 D. Supply Voltage
 1: 1.8V/ 2.5V/ 3.3V Compatible
 E. Frequency Tolerance*
 6: ± 50 ppm

- F. Symmetry (Duty Ratio) and Enable/Disable Function
 E: Symmetry: 45% to 55% with Stand-by Function
 G. For Automotive

Packing (Tape & Reel 2,000pcs/Reel)

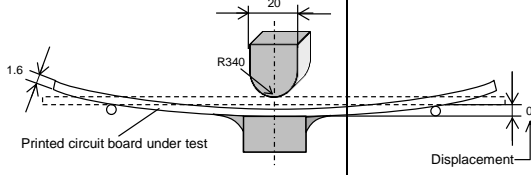
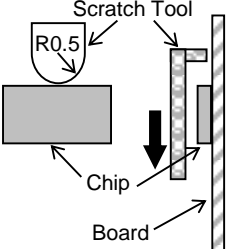
*Over All Conditions:

Include initial tolerance, operating temperature range, rated power supply voltage change, load change, aging (1year @+25°C), shock and vibration

7. Environmental Characteristics

7-1. Environmental Characteristics (Based on AEC-Q200 Rev. D)

AEC-Q200 No	Items	Conditions	Reference	Criteria of Acceptance	Sample Size [PCS]
3	High Temperature Exposure (Storage)	+125°C 1000 hrs. Unpowered.	MIL-STD-202 Method 108	Satisfy Electrical Characteristics.	77
4	Temperature Cycling	1000cycles (-55 to +125°C)	JESD22 Method JA-104	Satisfy Electrical Characteristics.	77
6	Moisture Resistance	+25°C, +65°C 90%RH 10cycles 24 hrs/1cycle. Unpowered. Steps 7a & 7b not required.	MIL-STD-202 Method 106	Satisfy Electrical Characteristics. Clause 13 shall be also satisfied.	77
7	Biased Humidity	+85°C, 85%RH, 1000 hrs. $V_{CC}=3.63V$, $CL=15pF$	MIL-STD-202 Method 103	Satisfy Electrical Characteristics.	77
8	Operational Life	+125°C, 1000 hrs. $V_{CC}=3.63V$, $CL=15pF$	MIL-STD-202 Method 108	Satisfy Electrical Characteristics.	77
9	External Visual	Magnification 10x	MIL-STD-883 Method 2009	Thing that abnormality is not found in externals. (Inspect device construction, marking and workmanship. Electrical Test not required.)	30
10	Physical Dimension	-	JESD22 Method JB-100	Satisfy Approval Sheet	30
12	Resistance to Solvents	Magnification 10x	MIL-STD-202 Method 215	Thing that abnormality is not found in externals.	5
13	Mechanical Shock	100G/6ms/Half-sine Velocity change 12.3 (Vi)ft/sec	MIL-STD-202 Method 213	Satisfy Electrical Characteristics.	30
14	Vibration	10 to 2000Hz. 5g's for 20 minutes 12 cycles each of 3 orientations.	MIL-STD-202 Method 204	Satisfy Electrical Characteristics.	30
15	Resistance to Soldering Heat	Soaking:+260 \pm 5°C, 10 \pm 1sec	MIL-STD-202 Method 210	Satisfy Electrical Characteristics.	30
16	Thermal Shock	-55°C/+125°C. 300Cycles, Max. transfer time 20 sec. Dwell time 5 min. Air-Air.	MIL-STD-202 Method 107	Satisfy Electrical Characteristics.	30
17	ESD	Human Body Model: 100pF/1500ohm/500~2000V 5 pulses	AEC-Q200-002	Satisfy Electrical Characteristics.	15
18	Solderability	8 hrs. steam age +215°C solder temperature 5 second dwell	J-STD-002	Dipped potion: Minimum 95% coverage	15
19	Electrical Characterization	-	Approval Sheet	Satisfy Approval Sheet	30 x 3Lot

AEC-Q200 No	Items	Conditions	Reference	Criteria of Acceptance	Sample Size [PCS]
21	Board Flex	<p>It pressurizes in the direction of the arrow, it pressurizes at the speed of 2mm in bend width about 0.5mm/sec, and it maintains it for 60 seconds.</p> 	AEC-Q200-005	Satisfy Electrical Characteristics. Without looseness or crack etc.	30
22	Terminal Strength (SMD)	<p>The static load of 1.8Kg is added in the direction of the arrow and it maintains it in the prime fields of parts for 60 sec with a scratch treatment device of R0.5.</p> 	AEC-Q200-006	Satisfy Electrical Characteristics. Without looseness or crack etc.	30

After above test, measurement shall be done after leaving sample in room temperature for 2 hours.

Table 3

7-2 Based on AEC-Q100 Rev. G
TEST GROUP A

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
PC	Preconditioning	JESD22 A113 J-STD-020	Satisfy Electrical Characteristics.	77
THB or HAST	Temperature-Humidity-Bias or Biased HAST	JESD22-A101 or 110	AEC-Q200 Biased Humidity	77
AC or UHST or TH	Autoclave or Unbiased HAST or Temperature-Humidity (without Bias)	JEDEC JESD22-A102,118 or A101	AEC-Q200 Biased Humidity Test	77
TC	Temperature Cycling	JESD22-A104	AEC-Q200 Temperature Cycling	77
PTC	Power Temperature Cycle	JESD22-A105	N/A Max rated power is under 0.1W.	-
HTSL	High Temperature Storage Life	JESD22-A103	Satisfy Electrical Characteristics.	45

Table 4

TEST GROUP B

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
HTOL	High Temperature Operating Life	JESD22- A108	AEC-Q200 Operational Life	77
ELFR	Early Life Failure Rate	AEC Q100-008	Satisfy Electrical Characteristics	800
EDR	NVM Endurance, Data Retention, and Operational Life	AEC Q100-005	NA IC without memory, not applicable	---

Table 5

TEST GROUP C

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
ALL GROUP C	---	---	NA Not Wire Bonding	---

Table 6

TEST GROUP D (Compatible IC MAKER DATA)

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
EM	Electromigration	JESD61	Process Data	---
TDDDB	Time Dependent Dielectric Breakdown	JESD35	Process Data	---
HCI	Hot Carrier Injection	JESD60 & 28	Process Data	---
NBTI	Negative Bias Temperature Instability	JESD90	N/A	---
SM	Stress Migration	JESD61,87 & 202	Process Data	---

Table 7

TEST GROUP E

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
TEST	Pre- and Post-Stress Function/Parameter	Specification	0 fails	ALL
HBM / MM	Electrostatic Discharge Human Body Model / Machine Model	AEC Q100-002 Q100-003	HBM Over 2KV MM Over 200V	18
CDM	Electrostatic Discharge Charged Device Model	AECQ100-011	0 Fails 750V corner pins, 500V all other pins	6
LU	Latch-Up	AECQ100-004	0 fails	6
ED	Electrical Distributions	AECQ100-009	Satisfy Electrical Characteristics	30
FG	Fault Grading	AECQ100-007	NA	---
CHAR	Characterization	AEC Q003	AEC-Q200 acceptable	---
GL	Electrothermally-Induced Gate Leakage	AECQ100-006	NA	---
EMC	Electromagnetic Compatibility	SAE J1752/3	For Information only	6
SC	Short Circuit Characterization	AEC Q100-012	N/A	---
SER	Soft Error Rate	JESD89-1 or JESD89-2 & JESD89-3	NA Non Volatile Memory IC	--

Table 8

TEST GROUP F

AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
PAT	Process Average Testing	AEC Q001	For Information only	ALL
SBA	Statistical Bin/Yield Analysis	AEC Q002	For Information only	ALL

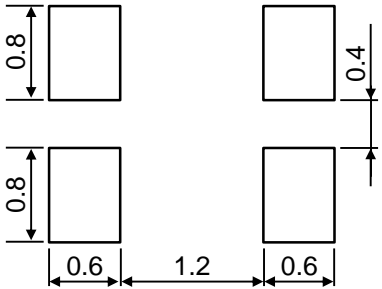
Table 9

TEST GROUP G

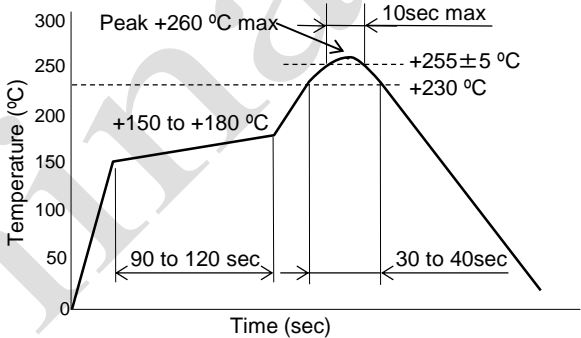
AEC-Q100 ABV	Stress	Reference	Criteria of Acceptance	Sample Size [PCS]
MS	Mechanical Shock	JESD22-B104	AEC-Q200 Mechanical Shock	39
VFV	Variable Frequency Vibration	JESD22-B103	AEC-Q200 Vibration	39
CA	Constant Acceleration	MIL-STD-883 Method 2001	Satisfy Electrical Characteristics	39
GFL	Gross/Fine Leak	MIL-STD-883 Method 1014	Satisfy Electrical Characteristics	39
DROP	Package Drop	---	NA NOT MEMS	---
LT	Lid Torque	MIL-STD-883 Method 2024	Over 0.5N-m	5
DS	Die Shear	MIL-STD-883 Method 2019	For Information only	5
IWV	Internal Water Vapor	MIL-STD-883 Method 1018	Satisfy Electrical Characteristics	3

Table 10

8. Recommended Land pattern and Soldering Guide



Unit: (mm)



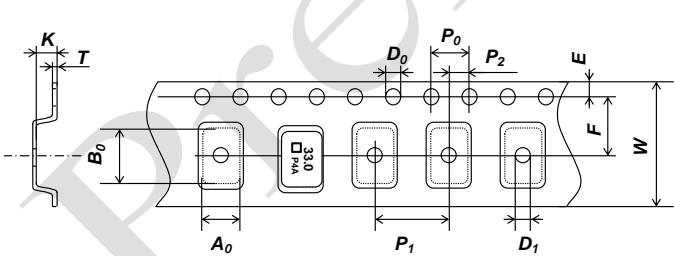
Note:
Since the part doesn't have Bypass Capacitor between V_{cc} and GND, Please mount high frequency type capacitor 0.01μF to the nearest position of oscillator.

- Available Reflow times: Maximum twice

Fig.4 Land pattern

Fig.5 Reflow profile (Lead Free Available)

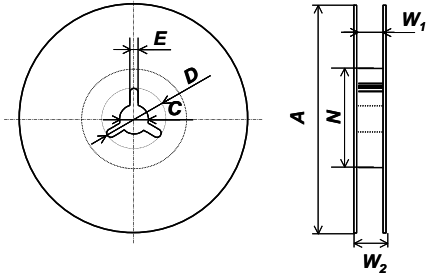
9. Taping Specifications



Unit: (mm)

Symbol	A₀	B₀	W	F	E
Dimensions	1.8±0.1	2.25±0.1	8.0±0.2	3.5±0.05	1.75±0.1
Symbol	P₁	P₂	P₀	D₀	T
Dimensions	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	0.2±0.05
Symbol	K	D₁			
Dimensions	0.9±0.1	1.1±0.1			

Fig.6 Emboss Carrier Tape



Unit: (mm)

Symbol	A	N	W₁
Dimensions	180 +0/-1.5	60+1/-0	9.0+0.3/-0
Symbol	W₂	C	D
Dimensions	11.4±1.0	13.0±0.2	21.0±0.8
Symbol	E		
Dimensions	2.0±0.5		

Fig.7 Reel

9-1. Taping Quantities

- The taping of per reel shall be packed 2,000 pcs.
- The parts shall be contained continuously in the pocket.

9-2. Leader and Blank Pockets

- The package shall be consisted of leader, blank pockets and loaded pocket as follows "Fig. 8".
- The power of peeling strength between top tape and carrier tape shall be 0.1N(10gf) to 0.7N(70gf) as follows "Fig. 9".



- A) Leader
 B) Blank Pocket (40mm to 320mm)
 A+B: 400mm to 560mm
 C) Load Pocket
 D) Blank Pocket (160mm minimum)

Fig.8 Packing Method

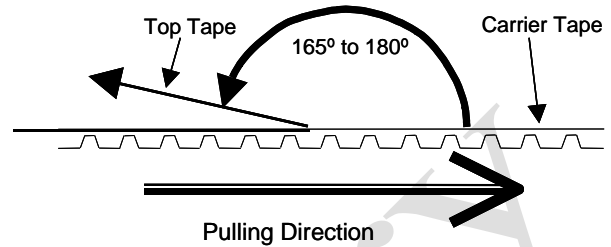


Fig.9 Peeling Strength

9-3. Reel Label

The reel label shall be consisted as below. (Based on EIAJ C-3 format)

- | | |
|-------------------------|------------------|
| A) Customer Part Number | D) Shipping Date |
| B) Lot No. | E) Vender Name |
| C) Quantities | |

9-4. Exterior Package Label

The oscillator shall be packed properly to avoid defect in transportation. The exterior package label shall be consisted as below.

- | | |
|-------------------------|------------------|
| A) Name of Customer | E) Quantities |
| B) P/O No. | F) Shipping Date |
| C) Customer Part Number | G) Vender Name |
| D) Lot No. | |

10. The agreement of this specifications

In case there is any obscure point or doubt concerning the contents of the specification, it shall be settled through consultation of both parties.

11. Remarks on Usages

A) Storage Conditions

The parts shall be stored in temperature range of -5 to +40°C, humidity 40 to 60% RH, and avoid direct sunlight. Then the parts shall be used within 6 months.

B) Handling Conditions

Although the part has protection circuit against static electricity, when excess static electricity is applied, the inside IC may get damaged.

Before mounting on the PCB, please make sure the direction of the part is correct. Otherwise the part of temperature will increase. And also the part will have some damages.

Please do not use the parts under the unfavorable condition such as beyond specified range in this specification.

Please do not use the parts under the condition, in the water or in the salt water also environment of dew or harmful gas.

Please make sure the condition of pick and place following pick up nozzle guideline.

Picking Method: Case of Head Unit 1.6 x 1.2mm (Inside Diameter)

The proper condition of pick and place will be different each equipment. Therefore, please check before testing.

C) Rework Condition

Please do not pick up Head Unit. We can't guaranty electrical performance and reliability.

D) Soldering Conditions

This product can respond to the general Pb-free reflow profile. The wave soldering cannot be supported.

E) Soldering in Mounting

In case of Solder paste and conductive glue contact product lid or product side face exception for product terminal it's possible to influence product characteristics.

Please be careful above contents.

F) Washing Conditions

Ultra sonic cleaning is available. However there is a possibility that Crystal in the part may cause damaged under certain condition. Therefore please test before using.

After washing, please dry the parts completely. Otherwise water drops between the parts and PCB may cause migration.

In case of using this part without above precaution, Kyocera is unable to guarantee the specific characteristics.